



CALL FOR PAPERS

IMPORTANT DATES

CALL FOR PAPERS DEADLINES

October 24, 2022 Regular Paper Submission

December 5, 2022 Transactions Paper Submissions

December 19, 2022 Author Notification

February 4, 2023 Final Manuscript Submission



TOPICS OF INTEREST

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems (CAS) Society and the world's premiere forum for researchers in the active fields of theory, design and implementation of circuits and systems. This is accomplished through technical conference sessions, poster sessions, live demonstration sessions, and publication of conference papers. ISCAS 2023 will be driven by the theme "Technology Disruption and Society" aiming to emphasize the potential of the CAS Society to find innovative solutions to challenges facing society today.

This year's meeting will highlight the following innovation themes:	Collecting contributions in all areas of Circuits and Systems, including but not limited to:
» Artificial Intelligence & Deep Learning	» Analog and Mixed Signal Circuits and Systems
» Big Data Processing	» Digital Integrated Circuits and Systems
» Internet of Things	» Power and Energy Circuits and Systems
» Distributed and Decentralized Systems	» Sensory Circuits and Systems
» Intelligent Video Analytics and Vision Systems	» Nonlinear Systems and Circuit Theory
» Zettabyte Communication Infrastructure	» Digital Signal Processing
» Storage Class Memories and Computational Storage	» Multimedia Systems and Applications
» Personalized Healthcare Systems	» Communications Circuits and Systems
» Brain: Innovative NeuroTechnologies	» Biomedical Circuits and Systems
» Disaster and Pandemic Prevention and Mitigation	» Neural Networks and Neuromorphic Engineering
 » Green and Sustainable Computing and Systems » Technologies for Responsible, Fair and Ethical IT 	» Beyond CMOS: Nanoelectronics and Heterogeneous System Integration
	» Education in Circuits and Systems

Paper Submission	Selected papers will be invited for possible publication either in the IEEE Transaction on Circuits and Systems – Part I, in the IEEE Transaction on Circuits and Systems – Part II, or in the IEEE Transaction on Biomedical Circuits and Systems.
About Monterey	Picture seaside cliffs and pristine beaches, where you might spot whales, sea otters and migrating birds. From famous writers' haunts to Spanish Missions, the history here is just as fascinating as the geography. Aside from the epic scenery, you'll savor unforgettable flavors from the area's award-winning food and wine scene. Plus, there are limitless opportunities for recreation, including world-class golf, shopping, kayaking, hiking and only 70 miles from Silicon Valley.

Please visit: iscas2023.org

IEEE ISGAS 2023 Eter International Symposium on Circuits and Systems



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